

Product/process change notification

PCN N° 2022-001-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Capacity extension and harmonization of mould compound for dedicated OptiMOS™ products in PG-TDSON-8 package at Tongfu Microelectronics Co. Ltd China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-07-11**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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► Products affected

Please refer to attached affected product list 1_cip22001_a

► Detailed change information

Subject	Capacity extension and harmonization of mould compound at Tongfu Microelectronics Co. Ltd. for PG-TDSON-8 package		
Reason	Expansion of assembly and test production to cover increasing customer demand, and enable flexible manufacturing		
Description	<u>Old</u>	<u>New</u>	
Assembly and final test location	■ Infineon Technologies Malaysia Sdn. Bhd., Melaka	■ Infineon Technologies Malaysia Sdn. Bhd., Melaka	
	and	and	
	■ Subcontractor ATX (Weihai) Inc., China	■ Subcontractor ATX (Weihai) Inc., China	
	and	and	
Mould Compound	■ Infineon Technologies Wuxi Co., Ltd., China	■ Infineon Technologies Wuxi Co., Ltd., China	
	and	and	
	■ Subcontractor Tongfu Microelectronics Co. Ltd., China (<u>partially</u>)*	■ Subcontractor Tongfu Microelectronics Co. Ltd., China	
	■ Hitachi CEL 1772	■ Hitachi CEL 9240	
	and		
	■ Hitachi CEL 9240		

* products released already with PCN 2019-001-A

► Product identification

Internal traceability via Baunumber, Lotnumber, date code and marking on device and external traceability via marking on device (details 3_cip22001_a)

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► Impact of change

NO change on electrical and thermal performance

NO impact on the device reliability as proven via product qualification and characterization.

NO impact on the electrical parameters and device processability at customer end. Assembly processes are optimized to meet product performance according to already applied Infineon specification

Update of package outline drawing in the datasheet (3_cip22001_a)

► Attachments

1_cip22001_a	affected product list
3_cip22001_a	customer information package

► Time schedule

■ Final qualification report	available
■ First samples available	on request
■ Intended start of delivery	2022-08-01 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local sales office.